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### MATERIALS

| Basic Linear Materials (Linear, Anisotropic, Temperature Dependent) | •         | •         | •         | •         | •       |
| Basic Nonlinear Materials (Hyper, Plasticity, Rate Independent, Isotropic, Concrete) | •         | •         | •         | •         | •       |
| Advanced Nonlinear Materials (Rate dependent, Anisotropic, Damage Models, Geomechanics Materials, Multiphysics) | •         | •         | •         | •         | •       |
| Field Dependent                      | •         | •         | •         | •         |         |
| Reactive Materials                   | •         | •         | •         | •         |         |
| Fracture Mechanics and Crack Growth | •         | •         | •         | •         |         |
| Material Designer                    | •         | •         | •         | •         |         |
| GRANTA Materials Data for Simulation | 7         | 7         | 7         |           |         |

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### Composite Materials

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### Structural Solver Capabilities

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### DURABILITY

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### MISCELLANEOUS AND USABILITY (CONTINUED)

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- **Full Support**
- **Limited Capability**
- **Requires more than 1 product**
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- ● Full Support
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## Dispersed Multiphase Flows (Multiphase)

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## REACTING FLOWS

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- ● Full Support
- ▲ Limited Capability
- ■ Requires more than 1 product
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### OTHER COUPLED INTERACTIONS

- **Aero-Vibro Acoustics**: ●
- **Acoustics-Structural**: ● ●
- **Fluid Magnetohydrodynamics**: ● ●

### EASE OF USE AND PRODUCTIVITY

- **Support ACT Simulation Apps**: ●
- **Mosaic-Enabled Meshing Technology**: ●
- **Task-Based Workflow - Watertight Geometries**: ●
- **Task-Based Workflow - Fault Tolerant Geometries**: ●
- **Directly Enter Expressions**: ● ●
- **Parallel Solving with ANSYS Cloud Launched from Desktop**: ●
### ELECTRONICS

#### LOW FREQUENCY ELECTROMAGNETICS

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- **Full Support**
- **Limited Capability**
- **Requires more than 1 product**

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- ● Full Support
- ▲ Limited Capability
- ■ Requires more than 1 product
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- Full Support
- Limited Capability
- Requires more than 1 product
### POWER AND SIGNAL INTEGRITY BOARD SIMULATION CAPABILITIES (CONTINUED)

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### RLCG PARASITIC EXTRACTION

| DCRL, ACRL & CG Solver                     | ●                           | ●                        | ●                         | ●                                |                            | ●        |                   | ●                    |
| IC Packaging RLCG IBIS Extraction for Signals & Power | ●                           | ●                        | ●                         | ●                                |                            | ●        |                   | ●                    |
| Touchpanel RLCG Unit Cell Extraction       | ●                           | ●                        | ●                         | ●                                |                            | ●        |                   | ●                    |
| Adaptive Meshing for Accurate Extraction   | ●                           | ●                        | ●                         | ●                                |                            | ●        |                   | ●                    |
| Bus Bar RLCG Extraction                    | ●                           | ●                        | ●                         | ●                                |                            | ●        |                   | ●                    |
| Power Inverter & Converter Component Extraction | ●                           | ●                        | ●                         | ●                                |                            | ●        |                   | ●                    |
| 3D Component Library                       | ●                           | ●                        | ●                         | ●                                |                            | ●        |                   | ●                    |
### ELECTRONICS COOLING

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- **Full Support**
- **Limited Capability**
- **Requires more than 1 product**
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- ▲ Full Support
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● Full Support  ▲ Limited Capability  ■ Requires more than 1 product
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### MODEL-BASED SYSTEMS ENGINEERING

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* Full Support  ▲ Limited Capability  ■ Requires more than 1 product
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- Full Support
- Limited Capability
- Requires more than 1 product
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- Full Support
- Limited Capability
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● Full Support  ▲ Limited Capability  ■ Requires more than 1 product
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(1) Discovery Live supports mildly compressible fluid flow up to ~Mach 0.3  
(2) Included with Discovery Standard and Ultimate  
(3) Add-on Module
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- **●** Full Support
- **▲** Limited Capability
- **■** Requires more than 1 product
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**HUMAN VISION**

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**OPTICAL DESIGN**

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| OPTICAL SENSORS                   |          |              |                 |                          |                          |                             |                               |                                |
| Field Of View                     |          |              |                 |                          |                          |                             |                               |                                |
| Export Sensor Grid as Geometry    |          |              |                 |                          |                          |                             |                               |                                |
| Camera Sensor                     |          |              |                 |                          |                          |                             |                               |                                |
| SPEOS Lens System Importer (ZEMAX OpticStudio) |          |              |                 |                          |                          |                             |                               |                                |
| LiDAR Sensor                      |          |              |                 |                          |                          |                             |                               |                                |
| Camera Sensor Post Processing     |          |              |                 |                          |                          |                             |                               |                                |

| HEAD-UP DISPLAY                   |          |              |                 |                          |                          |                             |                               |                                |
| HUD Optical Analysis              |          |              |                 |                          |                          |                             |                               |                                |
| HUD Optical Design                |          |              |                 |                          |                          |                             |                               |                                |
| HUD Visualisation                 |          |              |                 |                          |                          |                             |                               |                                |

| HPC - SPEOS                       |          |              |                 |                          |                          |                             |                               |                                |
| Default Number of Cores           | 4        | 4            | 4               |                          |                          |                             |                               |                                |
| Parallel Solving on Local PC      |          |              |                 |                          |                          |                             |                               |                                |

- • Full Support
- ▲ Limited Capability
- ▪ Requires more than 1 product
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- ● Full Support
- ▲ Limited Capability
- ■ Requires more than 1 product
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(2) Only for ANSYS SPEOS
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- **▲ Limited Capability**
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### MATERIALS SELECTION & RELATED TOOLS (CONTINUED)

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### DATA LIBRARY FOR INDUSTRY

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- ● Full Support
- ▲ Limited Capability
- ■ Requires more than 1 product